

## 1. General description

Ultrafast power diode in a SMC package.

## 2. Features and benefits

- Low on-state loss
- Low leakage current
- Low thermal resistance
- Surface-mountable package

## 3. Applications

- Switching mode power supply
- High frequency rectifiers in buck and fly-back circuits
- Discontinuous Current Mode (DCM) Power Factor Correction (PFC)
- Terminal Adapter
- Inverter freewheeling and protection diode
- TV Power and LED Power


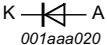
## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values	Unit
<b>Absolute maximum rating</b>				
$V_{RRM}$	repetitive peak reverse voltage		200	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse; $T_{lead} \leq 148\text{ °C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	3	A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\text{ }\mu\text{s}$ ; $T_{lead} \leq 148\text{ °C}$ ; square-wave pulse	6	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\text{ ms}$ ; $T_{j(init)} = 25\text{ °C}$ ; sine-wave pulse; <a href="#">Fig. 4</a>	160	A
		$t_p = 8.3\text{ ms}$ ; $T_{j(init)} = 25\text{ °C}$ ; sine-wave pulse	176	A

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		

6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
MUR320	SMC	MUR320J	Reel	3000	SMCS	16-Aug-2017
		MUR320,118				

7. Marking

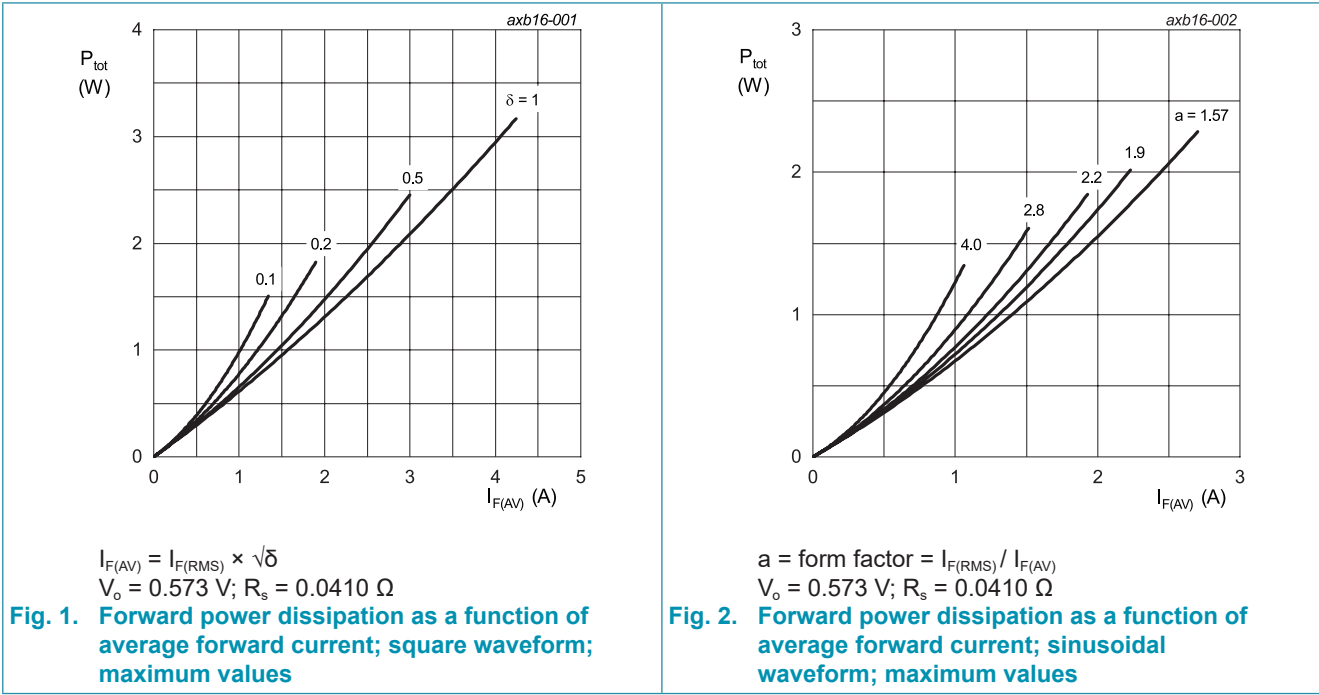
Table 4. Marking codes

Type number	Marking codes	
	Assembly factory: S	Assembly factory: E
MUR320	320JS	320JE

8. Limiting values

Table 5. Limiting values  
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage		200	V
$V_{RWM}$	crest working reverse voltage		200	V
$V_R$	reverse voltage	DC	200	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse; $T_{lead} \leq 148\text{ }^{\circ}\text{C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	3	A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\text{ }\mu\text{s}$ ; $T_{lead} \leq 148\text{ }^{\circ}\text{C}$ ; square-wave pulse	6	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\text{ ms}$ ; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$ ; sine-wave pulse; <a href="#">Fig. 4</a>	160	A
		$t_p = 8.3\text{ ms}$ ; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$ ; sine-wave pulse	176	A
$T_{stg}$	storage temperature		-65 to 175	$^{\circ}\text{C}$
$T_j$	junction temperature		175	$^{\circ}\text{C}$



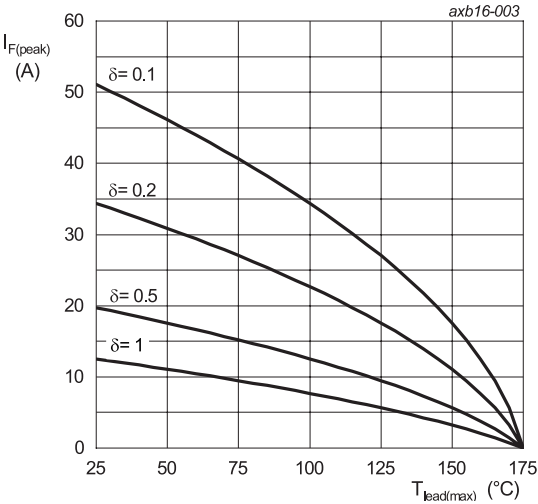


Fig. 3. Forward current as a function of lead temperature; maximum values

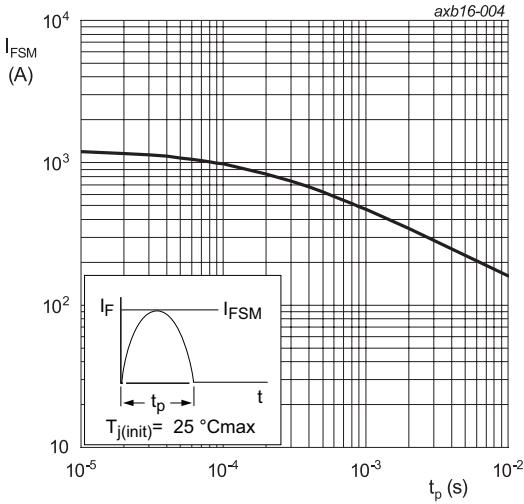


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-lead)}$	thermal resistance from junction to lead	<a href="#">Fig. 5</a>		-	-	11	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	70	-	K/W

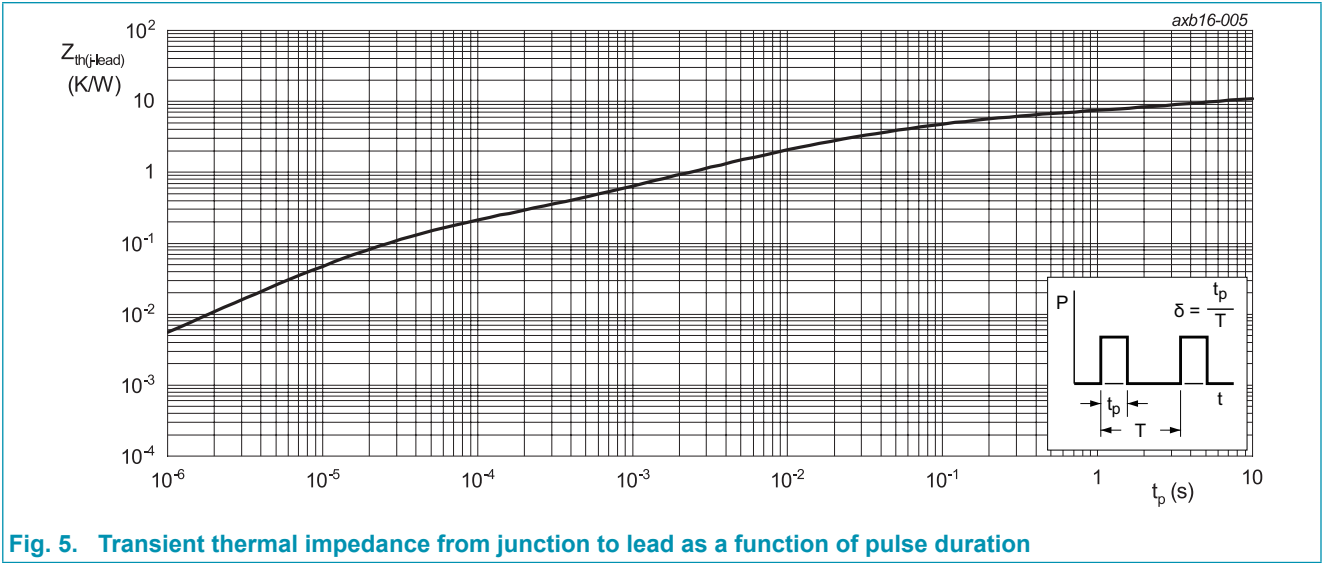
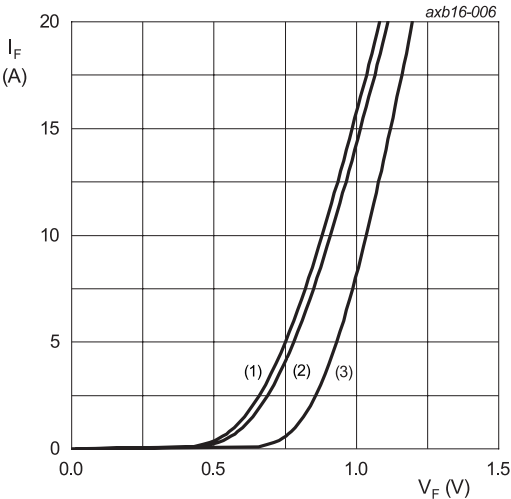


Fig. 5. Transient thermal impedance from junction to lead as a function of pulse duration

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 3 A; T <sub>J</sub> = 25 °C; <a href="#">Fig. 6</a>		-	-	0.875	V
		I <sub>F</sub> = 3 A; T <sub>J</sub> = 150 °C; <a href="#">Fig. 6</a>		-	-	0.71	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 200 V; T <sub>J</sub> = 25 °C		-	-	10	μA
		V <sub>R</sub> = 200 V; T <sub>J</sub> = 150 °C		-	-	400	μA
Dynamic characteristics							
Q <sub>r</sub>	reverse charge	I <sub>F</sub> = 3 A; V <sub>R</sub> = 100 V; dI <sub>F</sub> /dt = 100 A/us; T <sub>J</sub> = 25 °C; <a href="#">Fig. 7</a>		-	32	-	nC
		I <sub>F</sub> = 3 A; V <sub>R</sub> = 100 V; dI <sub>F</sub> /dt = 100 A/us; T <sub>J</sub> = 125 °C; <a href="#">Fig. 7</a>		-	77	-	nC
t <sub>rr</sub>	reverse recovery time	I <sub>F</sub> = 1 A; V <sub>R</sub> = 30 V; dI <sub>F</sub> /dt= 50 A/us; T <sub>J</sub> = 25 °C; <a href="#">Fig. 7</a>		-	-	35	ns
		I <sub>F</sub> = 0.5 A; I <sub>R</sub> = 1 A; I <sub>R(meas)</sub> = 0.25 A; T <sub>J</sub> = 25 °C; Step Recovery		-	-	28	ns
		I <sub>F</sub> = 3 A; V <sub>R</sub> = 100 V; dI <sub>F</sub> /dt = 100 A/us; T <sub>J</sub> = 25 °C; <a href="#">Fig. 7</a>		-	27	-	ns
		I <sub>F</sub> = 3 A; V <sub>R</sub> = 100 V; dI <sub>F</sub> /dt = 100 A/us; T <sub>J</sub> = 125 °C; <a href="#">Fig. 7</a>		-	41	-	ns
I <sub>RM</sub>	peak reverse recovery current	I <sub>F</sub> = 3 A; V <sub>R</sub> = 100 V; dI <sub>F</sub> /dt = 100 A/us; T <sub>J</sub> = 25 °C; <a href="#">Fig. 7</a>		-	2.4	-	A
		I <sub>F</sub> = 3 A; V <sub>R</sub> = 100 V; dI <sub>F</sub> /dt = 100 A/us; T <sub>J</sub> = 125 °C; <a href="#">Fig. 7</a>		-	3.8	-	A
E <sub>as</sub>	non-repetitive avalanche energy	I <sub>R</sub> = 1.2 A; T <sub>J(init)</sub> = 25 °C; L = 15 mH		10.8	-	-	mJ



V<sub>o</sub> = 0.573 V; R<sub>s</sub> = 0.0410 Ω  
(1) T<sub>J</sub> = 150 °C; typical values  
(2) T<sub>J</sub> = 150 °C; maximum values  
(3) T<sub>J</sub> = 25 °C; maximum values

Fig. 6. Forward current as a function of forward voltage

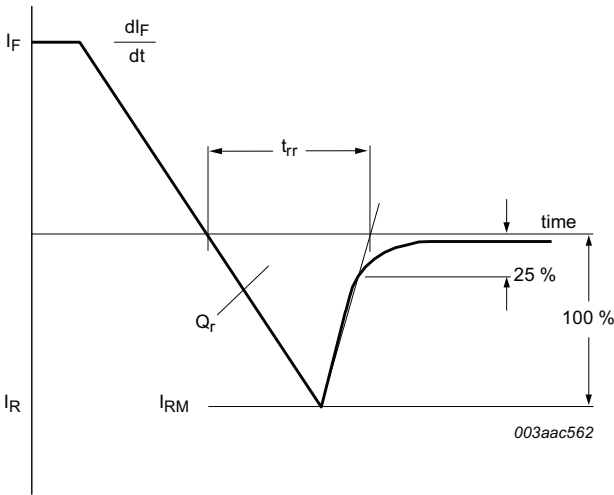
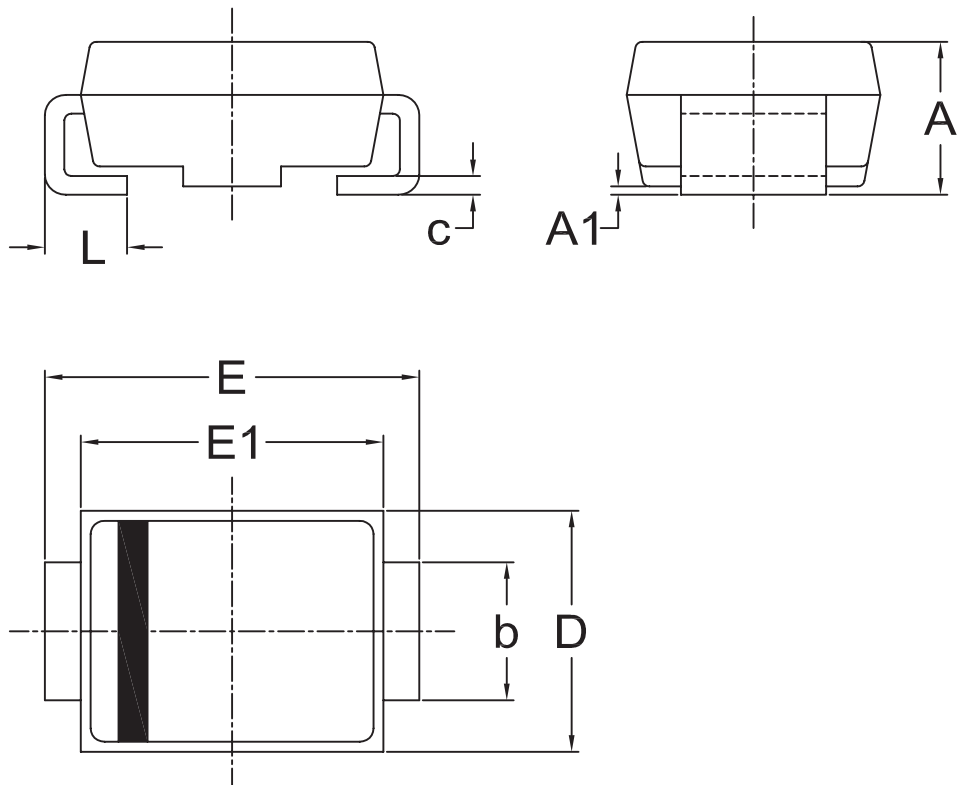


Fig. 7. Reverse recovery definitions; ramp recovery

11. Package outline



UNIT		A	A1	b	c	D	E	E1	L
mm	Max	2.40	0.22	3.18	0.31	6.22	8.13	7.11	1.52
	Min	2.01	0.05	2.92	0.15	5.59	7.70	6.60	0.76

Remark: Dimensions D and E1 do not include mold flash.

## 12. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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